To the Honorable Commissioner for Patents:

1. Name of Conveying Party(ies):
   Yoshihiko OHNO

Additional name(s) of conveying party(ies) attached?  □ Yes

3. Nature of Conveyance:
   ☑ Assignment  □ Merger
   □ Security Agreement  □ Change of Name
   □ Other

Execution Date:  October 20, 2000

4. Application number(s) or patent number(s):
   91755073

If the document is being filed together with a new application, the execution date of the application is:  October 20, 2000

A. Patent Application No(s).

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name:  MCDERMOTT, WILL & EMERY
   Internal Address:
   Street Address:  600 13th Street, N.W.
   City:  Washington  State:  DC  Zip:  20005

Additional numbers attached?  □ Yes

6. Total number of applications and patents involved:  1

7. Total fee (37 CFR 3.41)  $40.00
   ☑ Enclosed  □ Authorized to be charged to deposit account

8. Deposit account number:  500417

Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stephen A. Becker, 26,527

Name and Registration No. of Person Signing  Signature  Date

Total number of pages comprising cover sheet:  1

CMB No. 0851-0011 (exp. 4/94)

01-26-2001
101593968

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 50090-252

Ched original documents or copy thereto:

01-25/2001 DBYRNE 00000211 500417 09755073

DO NOT USE THIS SPACE

PATENT
REEL: 011450 FRAME: 0972
ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,
Yoshikazu OHNO

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

Mitsubishi Denki Kabushiki Kaisha
2-3, Marunouchi 2-chome
Chiyoda-ku, Tokyo 100-8310
JAPAN

its successors and assigns ( hereinafter designated “ASSIGNEE” ) the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE MANUFACTURING METHOD AND SEMICONDUCTOR DEVICE

for which an application for United States Letters Patent was executed on even date herewith.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the international Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE’s full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

Yoshikazu OHNO

Name: Yoshikazu OHNO

DATE SIGNED

October 20, 2000

PATENT
REEL: 011450 FRAME: 0973

RECORDED: 01/08/2001